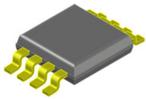
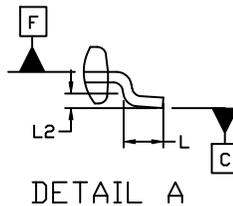
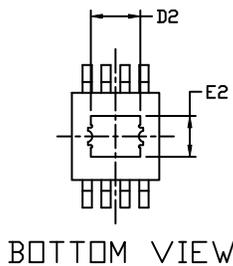
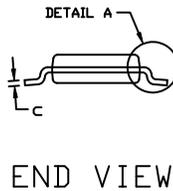
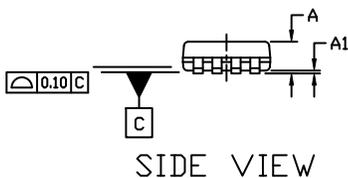
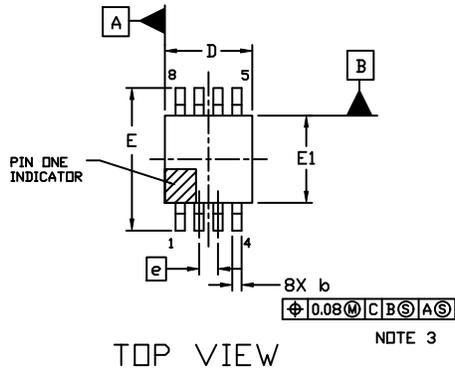


# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



## MSOP8 EP, 3x3 CASE 846AM ISSUE B

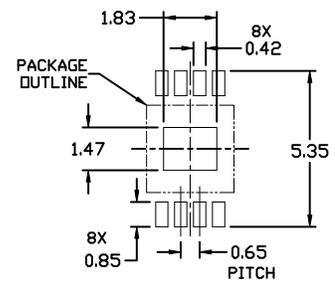
DATE 07 JAN 2022



### NOTES:

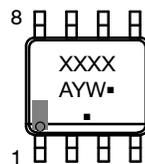
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS
- DIMENSION **b** DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.10 mm IN EXCESS OF MAXIMUM MATERIAL CONDITION.
- DIMENSION **D** DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 mm PER SIDE. DIMENSION **E** DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 mm PER SIDE. DIMENSIONS **D** AND **E** ARE DETERMINED AT DATUM **F**.
- DATUMS **A** AND **B** ARE TO BE DETERMINED AT DATUM **F**.
- A1** IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

DIM	MILLIMETERS	
	MIN.	MAX.
A	---	1.10
A1	0.05	0.15
b	0.25	0.40
c	0.13	0.23
D	2.90	3.10
D2	1.73	1.83
E	4.75	5.05
E1	2.90	3.10
E2	1.37	1.47
e	0.65 BSC	
L	0.40	0.70
L2	0.254 BSC	



\* FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERM/D.

### GENERIC MARKING DIAGRAM\*



- XXXX = Specific Device Code
- A = Assembly Location
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)  
\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	MSOP8 EP, 3X3	PAGE 1 OF 1

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